



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD90N06S4-05		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000983322						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		376.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.393	0.90	0.90	9023	9023
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		572	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		172	
	non noble metal	copper	7440-50-8	215.017	57.17	57.25	571744	572488
wire	non noble metal	aluminium	7429-90-5	45.572	12.12	12.12	121180	121180
encapsulation	organic material	carbon black	1333-86-4	0.858	0.23		2282	
	plastics	epoxy resin	-	15.019	3.99		39936	
	inorganic material	silicondioxide	60676-86-0	69.944	18.60	22.82	185986	228204
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9945	9945
plating	non noble metal	nickel	7440-02-0	0.091	0.02		241	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	242
solder	noble metal	silver	7440-22-4	0.074	0.02		196	
	non noble metal	tin	7440-31-5	0.059	0.02		157	
	non noble metal	lead	7439-92-1	2.822	0.75	0.79	7505	7858
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	copper	7440-50-8	19.177	5.10	5.11	50994	51060
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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